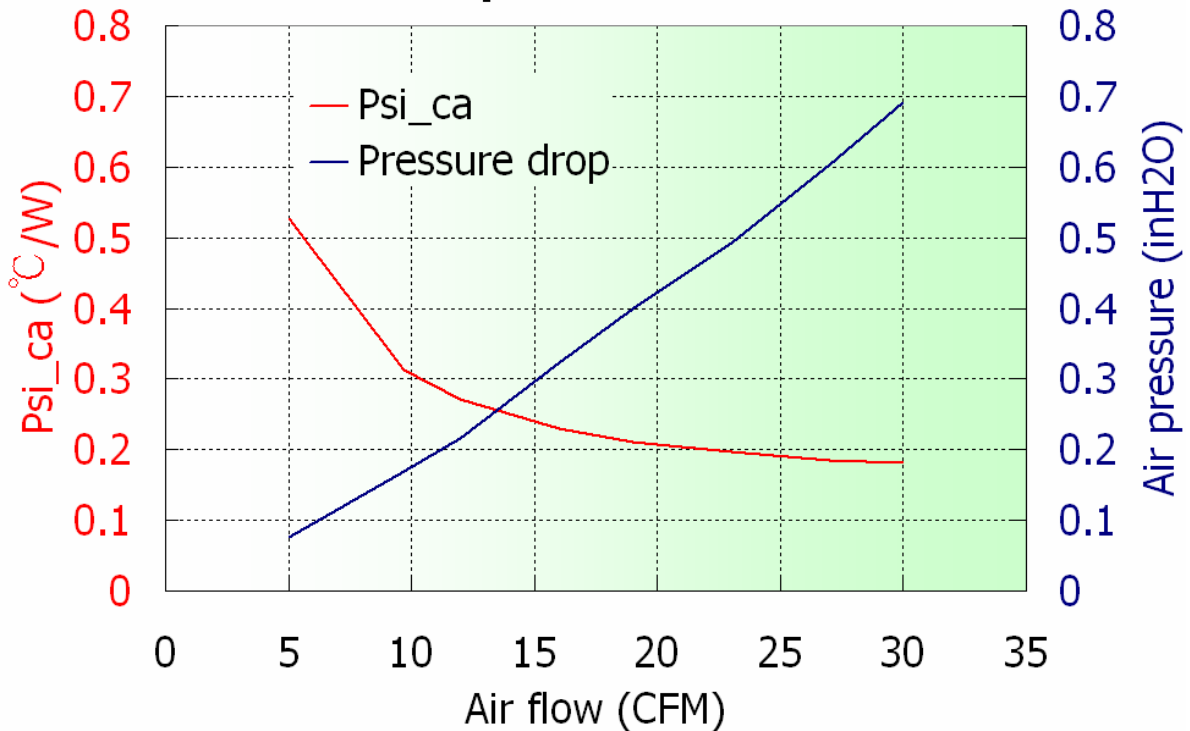


1. Application : Intel Nehalem/Westmere Socket 1366 1U Passive HSK
2. Material : Al1050 + Vapor chamber + SK7
3. Weight : 225g
4. Type : Soldering
5. Dimension : 90*90*25.5 [mm²]
6. Heat source size : 34*32 [mm²]
7. Thermal Interface Material :
Dow Corning TC-1996
8. Test Condition : Fully Ducted



Thermal performance curve



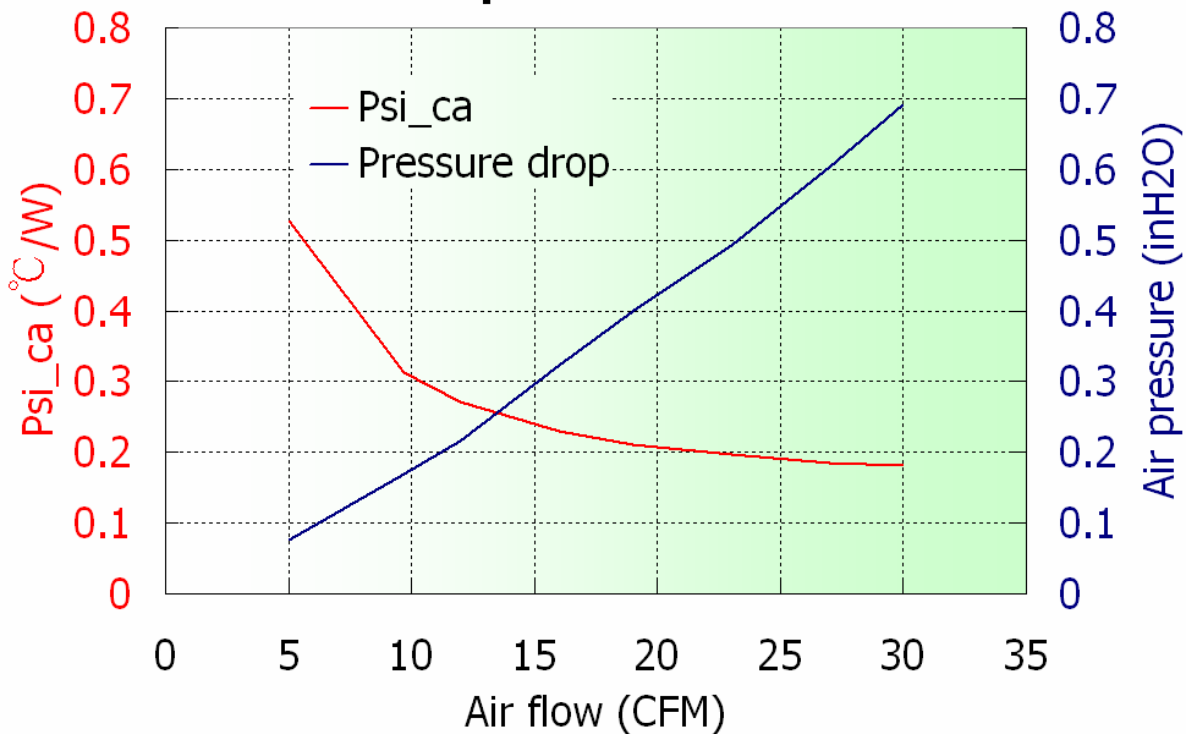
* All readings are typical values at rated voltage.
* Specifications are subject to change without notice



1. Application : Intel Nehalem/Westmere Socket 1366 1U Passive HSK
2. Material : Al1050 + Vapor chamber + SK7
3. Weight : 245g
4. Type : Soldering
5. Dimension : 90*90*27.0 [mm²]
6. Heat source size : 34*32 [mm²]
7. Thermal Interface Material : Dow Corning TC-1996
8. Test Condition : Fully Ducted



Thermal performance curve



* All readings are typical values at rated voltage.
 * Specifications are subject to change without notice

